

RoHS

COMPLIANT

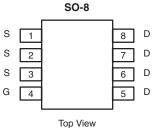
HALOGEN

FREE

Vishay Siliconix

N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
20	0.006 at V _{GS} = 10 V	20 ^e	27.5 nC			
20	0.007 at V_{GS} = 4.5 V	20 ^e	27.5110			

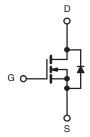


FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested ٠
- Compliant to RoHS Directive 2002/95/EC •

APPLICATIONS

- · Low-Side MOSFET for Synchronous Buck - Game Machine
 - PC



Ordering Information: Si4114DY-T1-E3 (Lead (Pb)-free) Si4114DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

ABSOLUTE MAXIMUM RATIN	IGS T _A = 25 °C,	unless other	wise noted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 16		
Continuous Drain Current (T _J = 150 °C)	$T_{C} = 25 °C$ $T_{C} = 70 °C$ $T_{A} = 25 °C$ $T_{A} = 70 °C$	- I _D -	20 ^e 18.2 15.2 ^{b, c} 12.1 ^{b, c}		
Pulsed Drain Current		I _{DM}	50	A	
Continuous Source-Drain Diode Current	T _C = 25 °C T _A = 25 °C	I _S	5.1 2.2 ^{b, c}		
Single Pulse Avalanche Current L = 0.1 mH		I _{AS}	30		
Avalanche Energy	L = 0.1 mm	E _{AS}	45	mJ	
Maximum Power Dissipation	$T_{C} = 25 °C$ $T_{C} = 70 °C$ $T_{A} = 25 °C$ $T_{A} = 70 °C$	- P _D -	5.7 3.6 2.5 ^{b, c} 1.6 ^{b, c}	w	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	39	50	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	18	22	0/10		

Notes:

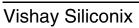
a. Based on $T_C = 25 \ ^{\circ}C$.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 85 °C/W.

e. Package limited.





Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					1		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 050 4		19		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.3			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		2.1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 16 V$			± 100	nA	
		$V_{DS} = 20 V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	IDSS	V_{DS} = 20 V, V_{GS} = 0 V, T_{J} = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V _{GS} = 10 V, I _D = 10 A		0.0049	0.006		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 7 \text{ A}$		0.0056	0.007	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 10 A		55		S	
Dynamic ^b	1 1					I	
Input Capacitance	C _{iss}			3700		pF	
Output Capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		745			
Reverse Transfer Capacitance	C _{rss}			315			
Total Gate Charge		$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		62	95		
	Q_g			27.5	42		
Gate-Source Charge	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_D = 10 A		8.0		- nC	
Gate-Drain Charge	Q _{gd}			6.0			
Gate Resistance	Rg	f = 1 MHz	0.15	0.7	1.4	Ω	
Turn-On Delay Time	t _{d(on)}			30	55	-	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2 Ω		13	25		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D} \cong \text{5}$ A, V_GEN = 4.5 V, R_g = 1 Ω		60	100		
Fall Time	t _f			30	55		
Turn-On Delay Time	t _{d(on)}			13	25	ns	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2 Ω		9	18		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}{\cong}5$ A, V_GEN = 10 V, R_g = 1 Ω		38	65		
Fall Time	t _f			8	16		
Drain-Source Body Diode Characterist	ics			1			
Continuous Source-Drain Diode Current	ا _S	T _C = 25 °C			5.1	^	
Pulse Diode Forward Current ^a	I _{SM}				50	A	
Body Diode Voltage	V _{SD}	I _S = 2 A		0.71	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			26	50	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 10.0 d/dt = 100.0/trace		16	30	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{ T}_J = 25 ^\circ\text{C}$		13			
Reverse Recovery Rise Time				13		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

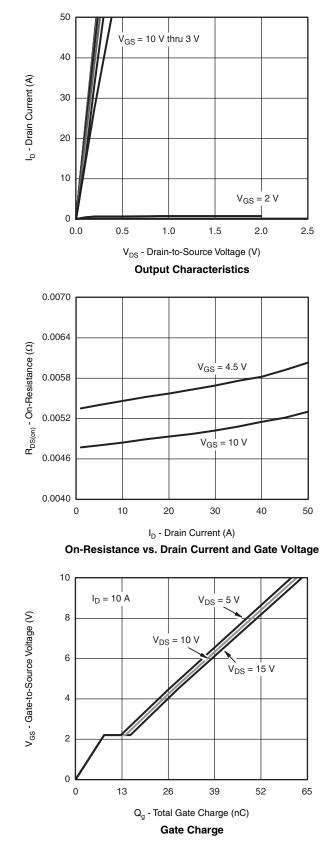
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

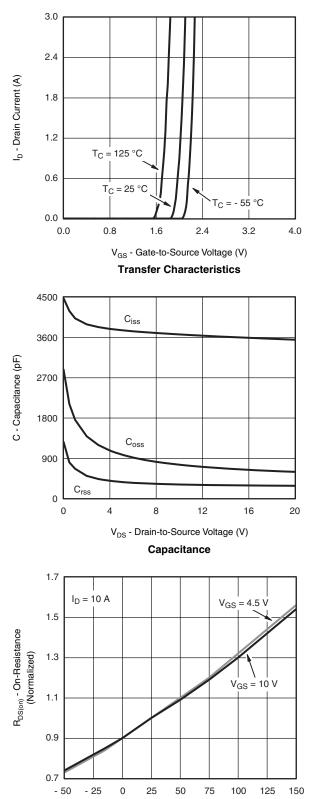




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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





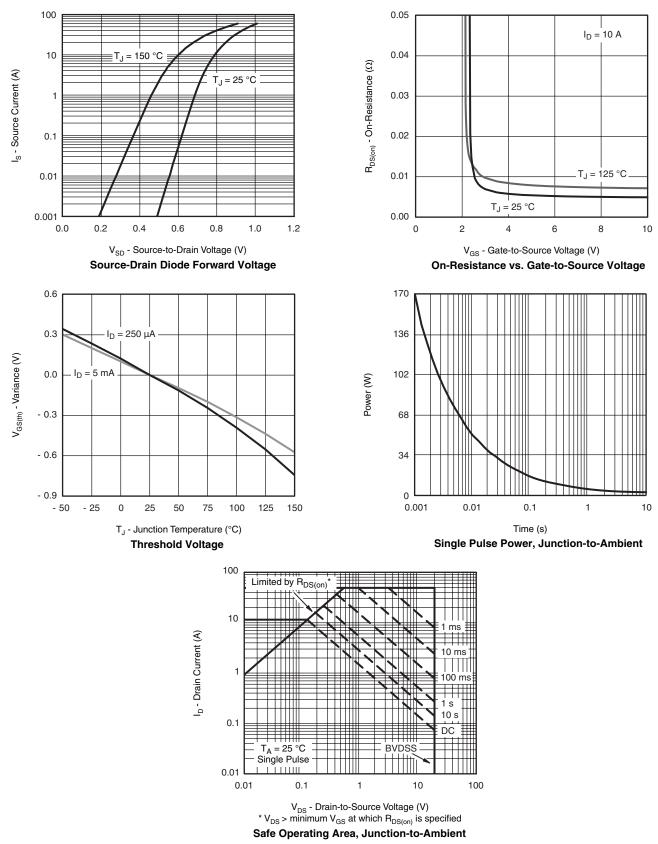
Document Number: 68394 S09-0764-Rev. B, 04-May-09 T_{.1} - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

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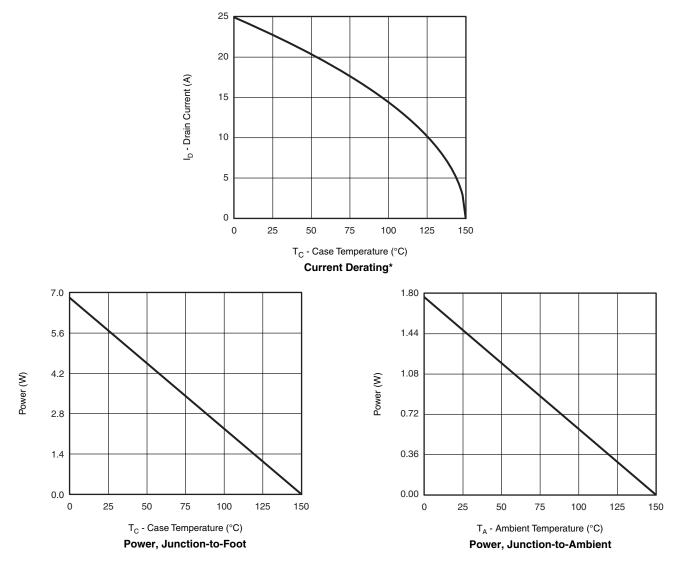
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Si4114DY Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

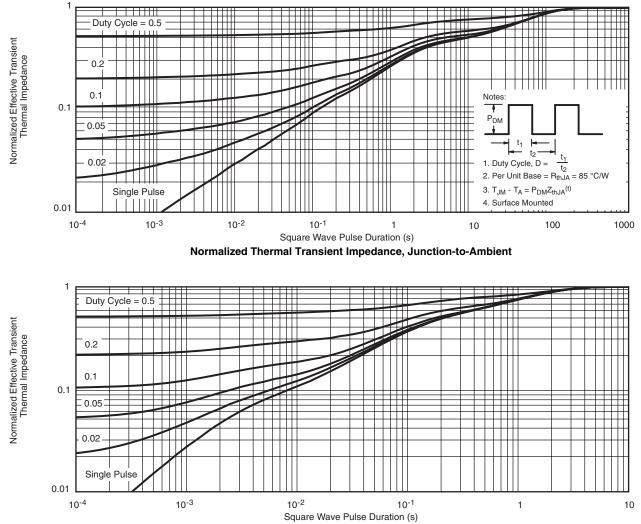


* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68394.



Package Information

Vishay Siliconix

SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

Application Note 826

Vishay Siliconix



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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